

# EUDET planning - FEV -

CALICE technical meeting on EVO  
Thursday, May 5  
14:00 CEST

# FEV7s

- CIP: chip in package
  - Ordered, to be received by june
- COB: chip on board
  - Being routed
  - Cost!
  - Manufacturer selection
  - Planned for October
- 4 ROCs
- 1 partition
- 2x36 pins edge connectors

# FEV8

- When FEV7\_CIP are validated
  - Pcb
  - Bonding
  - Resin
  - Slab assembly
- Final thickness
  - 1.2 mm budget
- Planned for Q1'10 ?